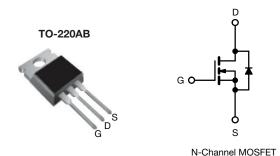
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



| PRODUCT SUMMARY | | | | |
|--|------------------------------|-----|--|--|
| V _{DS} (V) at T _J max. 650 | | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V 0.070 | | | |
| Q _g max. (nC) | 6 | 3 | | |
| Q _{gs} (nC) | 19 | | | |
| Q _{gd} (nC) | 1 | 0 | | |
| Configuration | Sin | gle | | |

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

| ORDERING INFORMATION | |
|---------------------------------|-----------------|
| Package | TO-220AB |
| Lead (Pb)-free and halogen-free | SIHP080N60E-GE3 |

| ABSOLUTE MAXIMUM RATINGS (T _C | = 25 °C, unl | ess otherwis | se noted) | | | |
|--|-------------------------|---|-----------------|-------|--------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | V _{DS} | 600 | V | | |
| Gate-source voltage | | | V_{GS} | ± 30 | | |
| Continuous drain surrent /T 150 °C) | \/ at 10.\/ | $T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$ | | 35 | | |
| Continuous drain current (T _J = 150 °C) | V _{GS} at 10 V | T _C = 100 °C | Ι _D | 22 | Α | |
| Pulsed drain current ^a | | I _{DM} | 96 | 1 | | |
| Linear derating factor | | | | 1.8 | W/°C | |
| Single pulse avalanche energy b | | | E _{AS} | 226 | mJ | |
| Maximum power dissipation | | P_{D} | 227 | W | | |
| Operating junction and storage temperature range | | T _J , T _{stg} | -55 to +150 | °C | | |
| Drain-source voltage slope | | T _J = 125 °C | dv./d+ | 100 | 1//20 | |
| Reverse diode dv/dt ^d | | • | dv/dt | 10 | - V/ns | |
| Soldering recommendations (peak temperature) ^c For 10 s | | 10 s | | 260 | °C | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



Vishay Siliconix

| THERMAL RESISTANCE RATI | NGS | | | |
|----------------------------------|-------------------|------|------|-------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R_{thJA} | - | 62 | °C/W |
| Maximum junction-to-case (drain) | R _{thJC} | - | 0.55 | G/ VV |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|-------|-------|------|
| Static | | | | | | | • |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 600 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | Reference to 25 °C, I _D = 1 mA | | 0.64 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | V _{GS} , I _D = 250 μA | 3.0 | - | 5.0 | V |
| Only and and and | 1 | , | V _{GS} = ± 20 V | | - | ± 100 | nA |
| Gate-source leakage | I_{GSS} | , | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 1 | μΑ |
| Zoro goto voltago drain ourrent | | V _{DS} = | V _{DS} = 600 V, V _{GS} = 0 V | | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 480 V | , V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 17 A | - | 0.070 | 0.080 | Ω |
| Forward transconductance a | 9 _{fs} | V _{DS} = 20 V, I _D = 17 A | | - | 4.6 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V, | | - | 2557 | - | pF |
| Output capacitance | C _{oss} | Ţ , | $V_{DS} = 3V$, $V_{DS} = 100 V$, | | 105 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1 MHz | | - | 6 | - | |
| Effective output capacitance, energy related ^a | $C_{o(er)}$ | V 0V/1 400V/V 0V | | - | 79 | - | |
| Effective output capacitance, time related ^b | $C_{o(tr)}$ | V _{DS} = 0 V | $V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$ | | 499 | - | |
| Total gate charge | Q_g | | | - | 42 | 63 | |
| Gate-source charge | Q_{gs} | $V_{GS} = 10 \text{ V}$ | V _{GS} = 10 V I _D = 17 A, V _{DS} = 480 V | | 19 | - | nC |
| Gate-drain charge | Q_gd | | | - | 10 | - | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 480 V, I _D = 17 A, | | - | 31 | 62 | |
| Rise time | t _r | | | - | 96 | 144 | ne |
| Turn-off delay time | $t_{d(off)}$ | V _{GS} = | $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$ | | 37 | 74 | ns |
| Fall time | t _f | | | | 31 | 62 | |
| Gate input resistance | R_{g} | f = 1 MHz, open drain | | 0.3 | 0.7 | 1.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | showing the | MOSFET symbol showing the | | - | 35 | |
| Pulsed diode forward current | I _{SM} | integral reverse p - n junction diode | | - | - | 96 | - A |
| Diode forward voltage | V _{SD} | T _J = 25 °C | T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V | | - | 1.2 | V |
| Reverse recovery time | t _{rr} | | | - | 441 | 882 | ns |
| Reverse recovery charge | Q _{rr} | $T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $di/dt = 80 \text{ A/µs}, V_R = 25 \text{ V}$ | | - | 5.2 | 10.4 | μC |
| Reverse recovery current | I _{RRM} | | | _ | 21 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

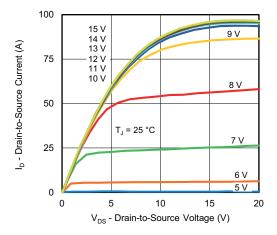


Fig. 1 - Typical Output Characteristics

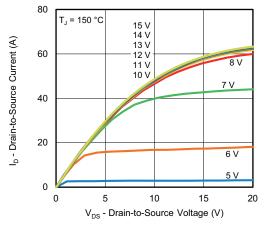


Fig. 2 - Typical Output Characteristics

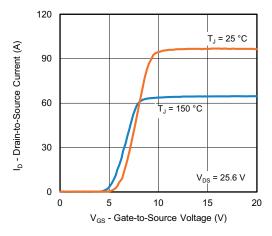


Fig. 3 - Typical Transfer Characteristics

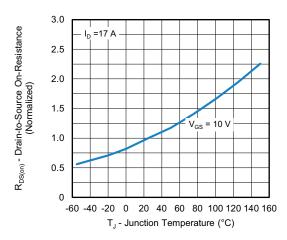


Fig. 4 - Normalized On-Resistance vs. Temperature

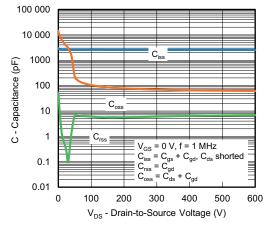


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

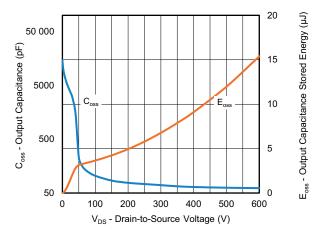


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



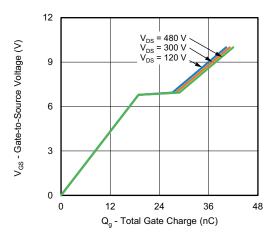


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

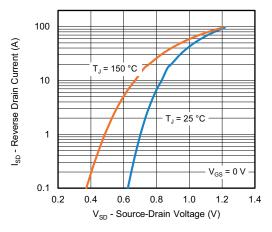


Fig. 8 - Typical Source-Drain Diode Forward Voltage

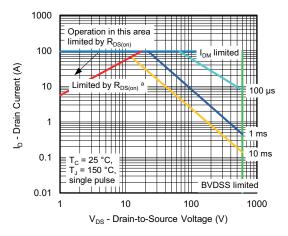


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

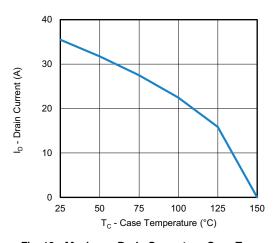


Fig. 10 - Maximum Drain Current vs. Case Temperature

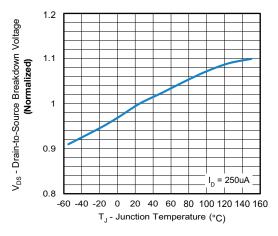


Fig. 11 - Temperature vs. Drain-to-Source Voltage



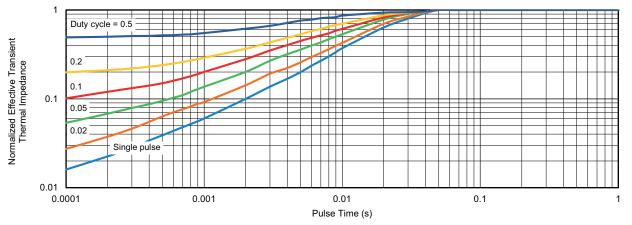


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

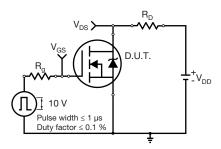


Fig. 13 - Switching Time Test Circuit

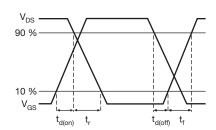


Fig. 14 - Switching Time Waveforms

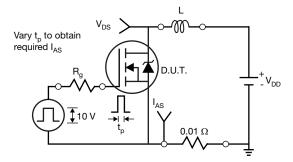


Fig. 15 - Unclamped Inductive Test Circuit

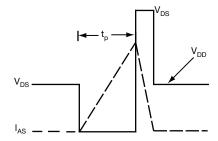


Fig. 16 - Unclamped Inductive Waveforms

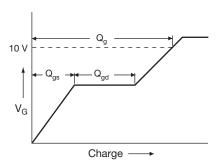


Fig. 17 - Basic Gate Charge Waveform

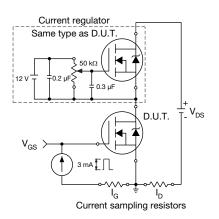
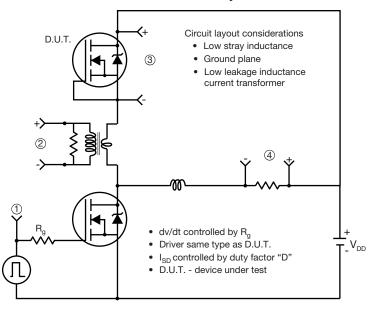


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



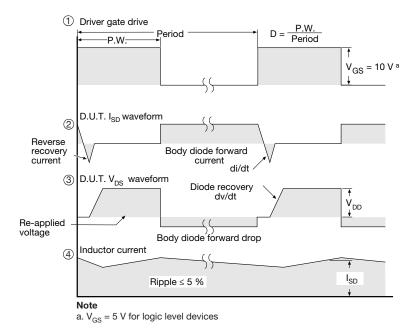
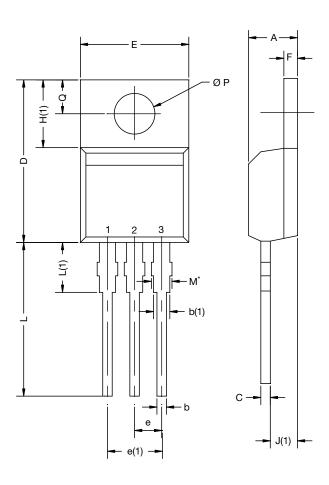


Fig. 19 - For N-Channel

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TO-220-1



| DIM. | MILLIM | METERS | INC | HES |
|------|--------|--------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| Α | 4.24 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.02 | 0.027 | 0.040 |
| b(1) | 1.14 | 1.78 | 0.045 | 0.070 |
| С | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.33 | 15.85 | 0.564 | 0.624 |
| Е | 9.96 | 10.52 | 0.392 | 0.414 |
| е | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.10 | 6.71 | 0.240 | 0.264 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.36 | 14.40 | 0.526 | 0.567 |
| L(1) | 3.33 | 4.04 | 0.131 | 0.159 |
| ØP | 3.53 | 3.94 | 0.139 | 0.155 |
| Q | 2.54 | 3.00 | 0.100 | 0.118 |

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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